/ Descriptions

VRS0; ṂṂ Ⱡ ᴥ Q ڜ P RV ʃ ѽ Ƶ ٦
Grxe0h Q0FKDQQH0 PRVIHW lq d VRS0; S0dvwlf Sdfndjh1

/ Features

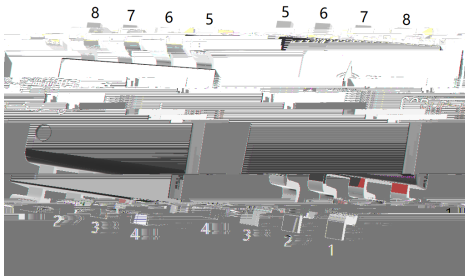
V_{DS}(V)=30V I_D=16A
$R_{DS(ON)}$@10V<8mΩ(Typ. 7.6mR)
$R_{DS(ON)}$)@4.5V<12mΩ(Typ. 10.8mR)
ɳ ғ β HF Product.

/ Applications

ᵻ PE2QE2X PSF2YJD ⓪ح ļ ق ذ ᴾ ª ℓ ں я ج Ѽ ʜ / ĭ ۷ GF0GF ɔ ד ۷ ۸ /ق U Ã ʜ
Klj k Iuhtxhqf| Srlqw0ri00rdg V|qfkurqrxv Exfn Frqyhuwhu iru PE2QE2X PSF2YJD/
Qhwz runlqj GF0GF Sr zhu V|vwhp/0rdg Vzlwfk1

/ Equivalent Circuit

/ Pinning



PIN1 χ S1 PIN 2 χ G1 PIN 3 χ S2 PIN 4 χ G2
PIN 5 χ D2 PIN 6 χ D2 PIN 7 χ D1 PIN 8 χ D1

/ Marking

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See Marking Instructions.

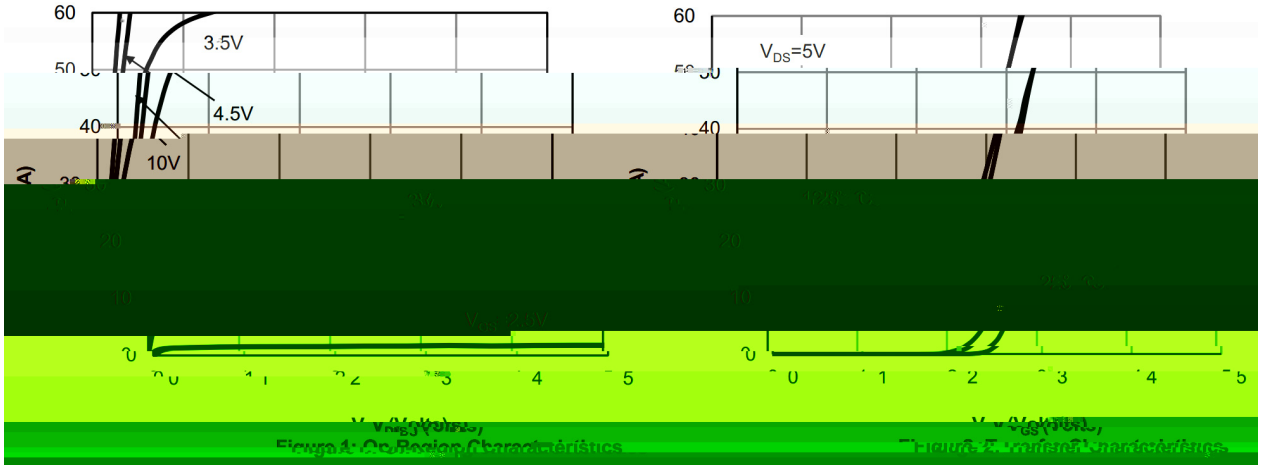
v ‴Ω Parameter	ϒ N Symbol	‴Ω Ö Rating	D Ꮋ Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	16	A
Pulsed Drain Current	I_{DM}	59	A
Power Dissipation	P_D	3.2	W
Junction and Storage Temperature Range	T_J,T_{STG}	-55 to +150	
Maximum Junction-to-Ambient	$R_{\theta JA}$(Steady-State)	39	/W

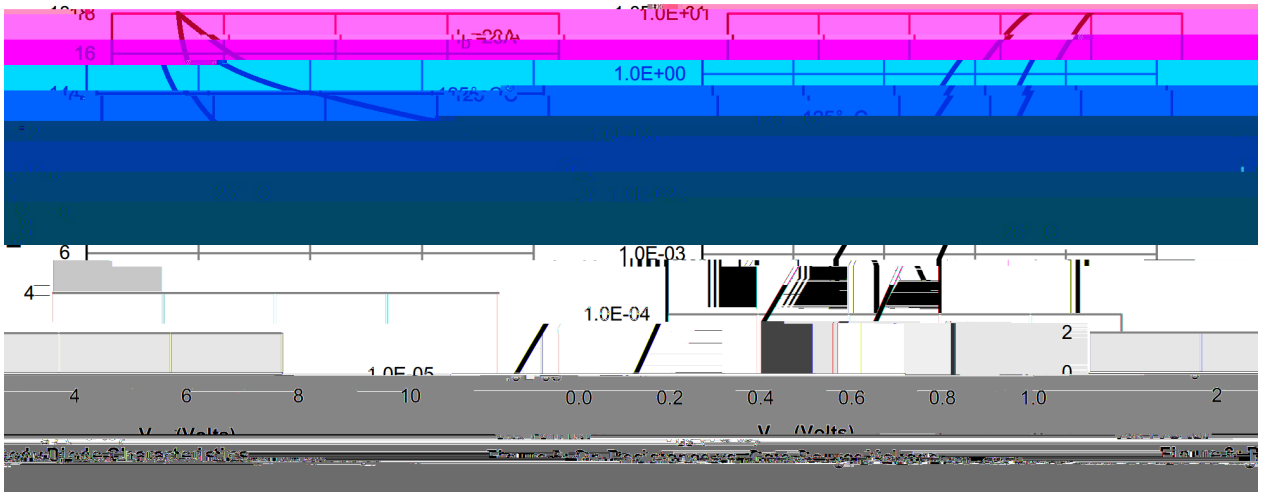
v ‴Ω Parameter	ϒ N Symbol	⅄ :ϯ ϒ Test Conditions	ѡ ṇ Ö Min	Ɛ ʒ Ö Typ	ѡ ᶻ Ö Max	D Ꮋ Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	30	35		V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=30V V_{GS}=0V			1	μA
Gate-Body leakage current	I_{GSS}	V_{GS}=±20V V_{DS}=0V			100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS} I_D=250μA	1.0	1.7		

on

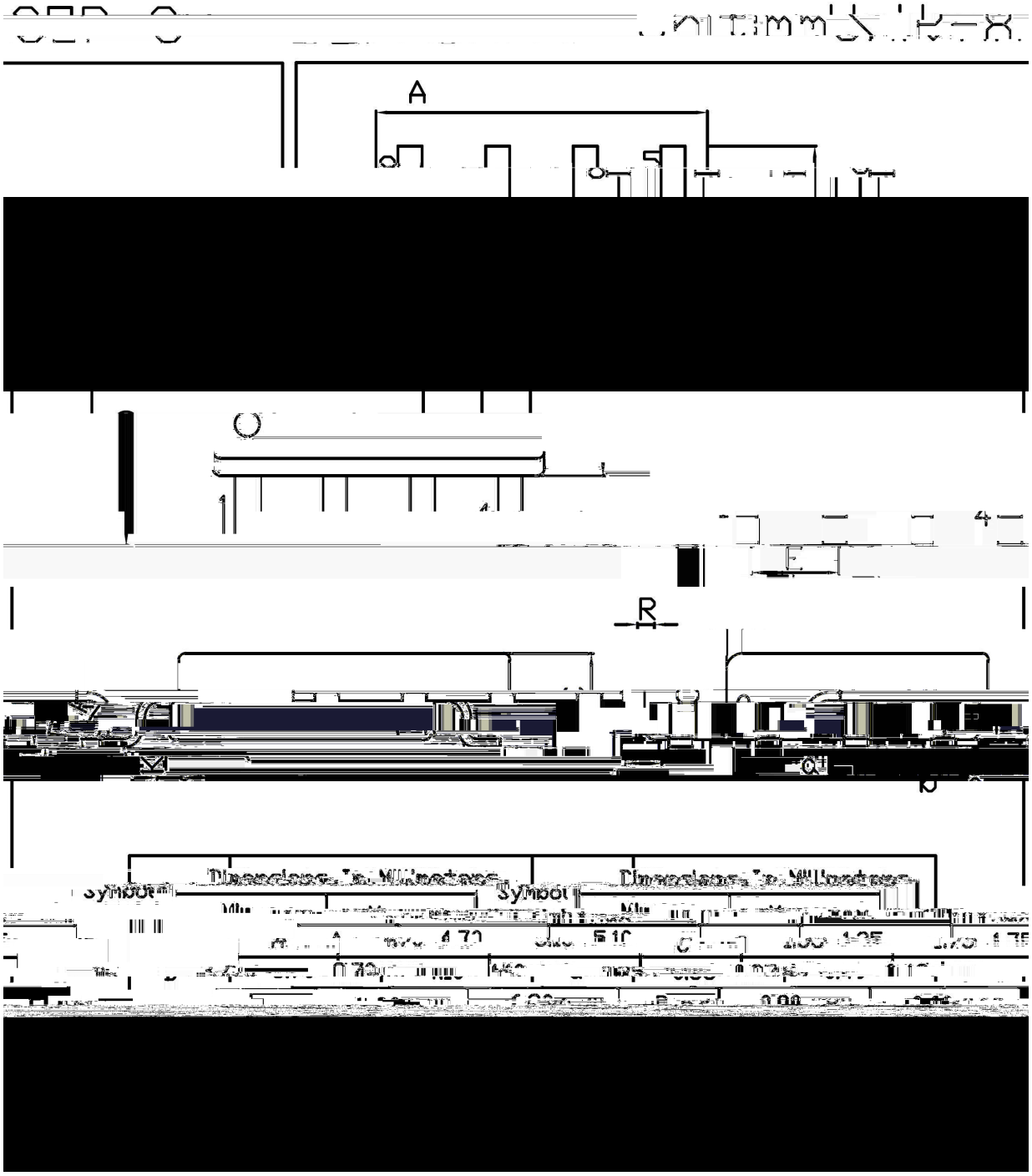
v ̈Ω Parameter	ϒ N Symbol	╨ ;ϯ ϒ Test Conditions	ϣ ṇ Ө Min	Ɛ ʒ Ө Typ	ϣ ᶻ Ө Max	ᴅ Ꮒ Unit
Turn-On Delay Time	$t_{d(on)}$	V_{DS}=15 V V_{GS}=10V R=10V =10V 880006 Tc(=15V)Tj385 1 Tf330008 0 T57TcTc( )Tɟ1<020d				

/ Electrical Characteristic Curve

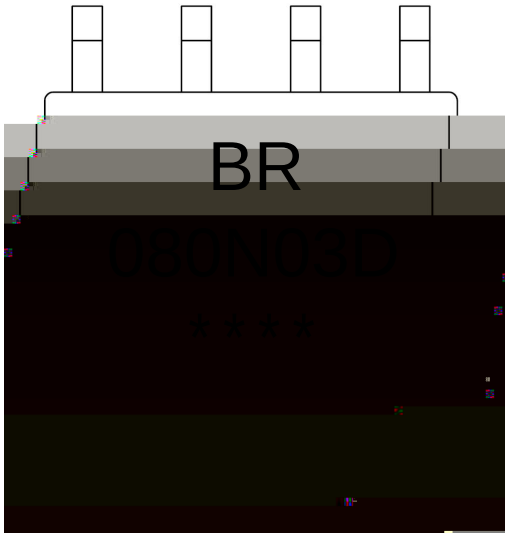




/ Package Dimensions



/ Marking Instructions



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BR χ	ѭ ҙ и Ґђ
080N03D χ	ѭ ҙ N Ґђ
**** χ	ѭ ӏ ғ ӈ̆ N Ґђ ӏ ҿ ӏ ғ ӈ̆ N Ψ ҏ

Note:

BR:	Company Code
080N03D:	Product Type
****:	Lot No. Code, code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

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1 Ĺ ♬ □ ỷ 150 Ḱ 180 ł ı `H ڑ 60 Ḱ 90sec;

2 Š Ө □ ỷ 245 ° 5 ł ı `H ڑ `Y ﾊ ㎞ 5 ° 0.5sec;

3 ì ˙ ﾘ ˛ ↄ ෯ ỷ ㎞ 2 Ḱ 10 ł /sec.

Note:

1.Preheating:150~180 ł , Time:60~90sec.

2.Peak Temp.:245 ° 5 ł , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ł /sec.

/ Resistance to Soldering Heat Test Conditions

605 ° 5 ł